



| ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-89 | | | | | |
|---|--------------------|-----------------------|------------------|--------------------|------------------------|
| STRESS | SAMPLE SIZE | DEVICE HR./CYC | CONDITION | TOTAL FAILS | FAIL PERCENTAGE |
| BOND INT | 240 | 120 000 | 200 °C + N2 | 0 | 0 |
| HAST | 1120 | 112 000 | 130 °C, 85 % RH | 0 | 0 |
| Pressure Pot | 1438 | 138 048 | 121°, 15 PSIG | 0 | 0 |
| Solder DUNK | 80 | 240 | 260 °C, 10 s | 0 | 0 |
| Solderability | 105 | 615 | 883 M2003 | 0 | 0 |
| Temp. Cycle | 2738 | 1 691 800 | -55 °C to 150 °C | 0 | 0 |